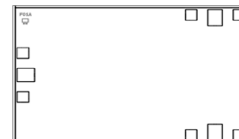


MMIC

# Power Splitter/Combiner Die

EP2KA-D+

2 Way-0° 50Ω 10 to 43.5 GHz



## The Big Deal

- Ultra-Wide Bandwidth, 10 to 43.5 GHz
- Excellent Amplitude Unbalance, 0.18 dB typ.

## Product Overview

Mini-Circuits' EP2KA-D+ is a MMIC 2-way 0° splitter/combiner Die designed for wideband operation from 10 to 43.5 GHz. Manufactured using GaAs IPD technology, it provides a high level of ESD protection and excellent reliability.

## Key Features

Feature	Advantages
Wideband, 10 to 43.5 GHz	One power splitter can be used in many applications, saving component count. Also ideal for wideband applications such as military and instrument.
Excellent Amplitude Unbalance, 0.18 dB and Good Phase Unbalance, 3-6 deg.	Excellent Amplitude and phase unbalance helps to accurately divide the input signals which is essential in test and measurement circuits.
Unpackaged Die	Enables user to integrate it directly into hybrids.



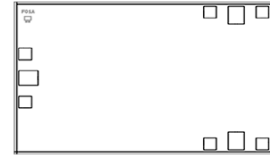
# MMIC Power Splitter/Combiner Die

## EP2KA-D+

2 Way-0° 50Ω 10 to 43.5 GHz

### Product Features

- Super wide bandwidth, 10 to 43.5 GHz
- Excellent amplitude unbalance, 0.18 dB typ.
- DC passing



### Applications

- Military
- 5G
- Instrumentation

#### +RoHS Compliant

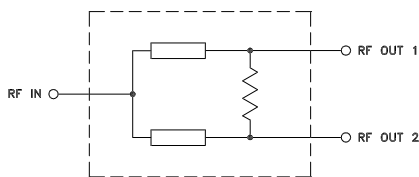
The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

**Ordering Information: Refer to Last Page**

### General Description

Mini-Circuits' EP2KA-D+ is a MMIC 2-way 0° splitter/combiner Die designed for wideband operation from 10 to 43.5 GHz. Manufactured using GaAs IPD technology, it provides a high level of ESD protection and excellent reliability.

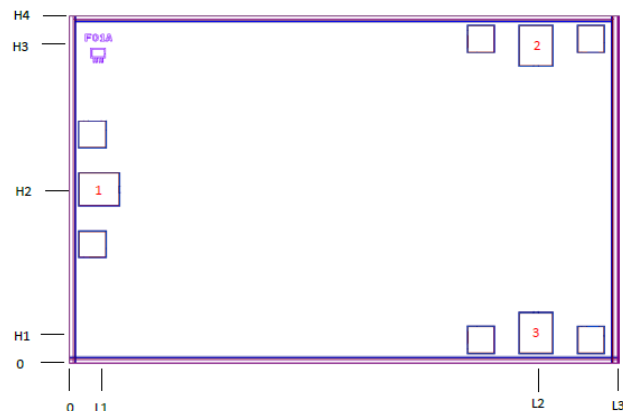
### Simplified Schematic and Pad Description



Pad#	Function
1	Sum Port (RF IN)
2	Port 1 (RF OUT 1)
3	Port 2 (RF OUT 2)
Die Bottom	Ground

Note: 1. Bond Pad material - Gold  
2. Bottom of Die is ground - Gold plated

### Bonding Pad Position



Dimensions in μm, Typical

L1	L2	L3	H1	H2	H3	H4	Thickness	Width	Length	Bond Pad #1 Size	Bond Pad #2 Size
112	1704	2000	112	635	1158	1270	100	1270	2000	150 x 125	150 x 125



Electrical Specifications at 25°C<sup>1</sup>

Parameter	Frequency (GHz)	Min.	Typ.	Max.	Unit
Frequency Range		10		43.5	GHz
Insertion Loss above 3.0 dB	10 - 20		0.8		dB
	20 - 25		0.5		
	25 - 30		0.9		
	30 - 40		1.5		
	40 - 43.5		2.2		
Isolation	10 - 20		17		dB
	20 - 25		26		
	25 - 30		22		
	30 - 40		26		
	40 - 43.5		29		
Phase Unbalance	10 - 20		3.7		Degree
	20 - 25		4.7		
	25 - 30		6.1		
	30 - 40		9.3		
	40 - 43.5		9.6		
Amplitude Unbalance	10 - 20		0.13		dB
	20 - 25		0.18		
	25 - 30		0.22		
	30 - 40		0.36		
	40 - 43.5		0.57		
VSWR (Port S)	10 - 20		1.6		:1
	20 - 25		1.1		
	25 - 30		1.4		
	30 - 40		1.4		
	40 - 43.5		1.5		
VSWR (Port 1-2)	10 - 20		1.3		:1
	20 - 25		1.2		
	25 - 30		1.3		
	30 - 40		1.4		
	40 - 43.5		1.4		

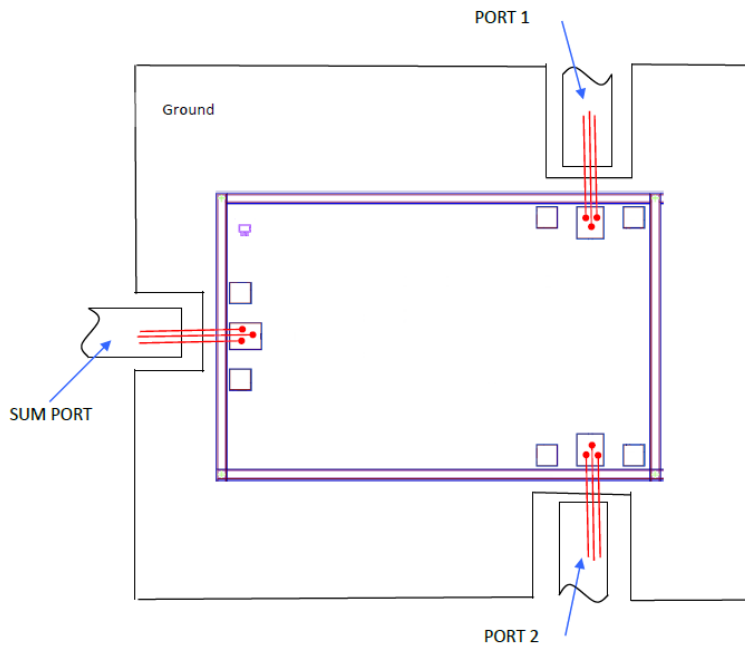
1. Tested in 2.5x3.5mm, Mini-Circuits 10-lead MCLP package.

## Maximum Ratings

Parameter	Ratings
Operating Temperature	-40°C to 85°C
Power Input (as a splitter)	1.25W
Internal Dissipation	0.63W
DC Current	300 mA

Permanent damage may occur if any of these limits are exceeded.

## Assembly Diagram



## Assembly and Handling Procedure

1. Storage  
Dice should be stored in a dry nitrogen purged desiccators or equivalent.
2. ESD  
MMIC dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static workstation. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.
3. Die Attach  
The Die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are DieMat DM6030HK-PT/H579 or Ablestik 84-1LMISR4. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total Die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufacturer's cure condition. It is recommended to use antistatic Die pick up tools only.
4. Wire Bonding  
Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the Die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.

<b>Additional Detailed Technical Information</b> <i>additional information is available on our dash board.</i>		
<b>Performance Data</b>	Data Table	
	Swept Graphs	
	S-Parameter (S3P Files) Data Set with and without port extension(.zip file)	
<b>Case Style</b>	Die	
<b>Die Ordering and packaging information (Note 5)</b>	Quantity, Package Small, Gel - Pak: 5,10,50, KGD* Medium†, Partial wafer: KGD*<790 Large†, Full wafer	Model No. EP2KA-DG+ EP2KA-DP+ EP2KA-DF+
	†Available upon request contact sales representative  Refer to <a href="#">AN-60-067</a>	
<b>Environmental Ratings</b>	ENV-80	

\*Known Good Dice ("KGD") means that the dice are taken from PCM good wafer and visually inspected in question have been subjected to Mini-Circuits while this is not definitive, it does help to provide a higher degree of confidence that dice are capable of meeting typical RF electrical parameters specified by Mini-Circuits.

## ESD Rating\*\*

Human Body Model (HBM): Class 2 (2000V to <4000V) in accordance with ANSI/ESD STM 5.1 - 2001

\*\* Tested in 2.5x3.5mm, Mini-Circuits 10-lead MCLP package.

### Additional Notes

- Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
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